

Unapproved Minutes
IEEE 802.3bm 40 Gb/s and 100 Gb/s Fiber Optic Task Force
Plenary meeting
July 16-18, 2013
Geneva, CH

Prepared by: Kapil Shrikhande

July 16, 2013

The meeting was called to order at 9:00 a.m. on July 16.
Kapil Shrikhande volunteered as Recording Secretary.

Round of introductions

All meeting materials for the July 2013 plenary meeting can be found at:
<http://www.ieee802.org/3/bm/public/jul13/index.html>

Agenda and General Information presentation

By: Dan Dove, Chair

See: http://www.ieee802.org/3/bm/public/jul13/dove_01a_0713_optx.pdf

The Chair asked if there was any opposition to approving the agenda for the meeting. The agenda was approved without any opposition.

The Chair asked if there was any opposition to approving the minutes from the May 2013 Task Force meeting. The May 2013 meeting minutes were approved without any opposition.

The Task Force decorum was presented.

The Task Force was reminded that photographs or recordings are not allowed without permission.

The Chair asked if there were any reporters present or if someone present might report on the activities of the meeting. There was no response.

The Chair read the IEEE patent policy. The Chair made a call for potentially essential patents. No one responded to the call for patents.

The rest of the agenda presentation was covered.

Start of presentations

Presentation # 1

Title: MMF ad hoc report

By: Jonathan King, Finisar (MMF Ad Hoc Chair)

See: http://www.ieee802.org/3/bm/public/jul13/king_01_0713_optx.pdf

Presentation # 2

Title: CAUI-4 ad hoc report

By: Ryan Latchman, Mindspeed (CAUI-4 Ad Hoc Chair)

See: http://www.ieee802.org/3/bm/public/jul13/latchman_01_0713_optx.pdf

Presentation # 3

Title: SMF Ad Hoc report

By: Pete Anslow, Ciena (SMF Ad Hoc Chair)

See: http://www.ieee802.org/3/bm/public/jul13/anslow_01_0713_optx.pdf

Presentation # 4

Title: Editor's opening report

By: Pete Anslow, Ciena (Task Force Chief Editor)

See: http://www.ieee802.org/3/bm/public/jul13/anslow_02_0713_optx.pdf

As per the agenda, the rest of the day will be spent on Comment Resolution. The Chair invited the Editorial team of the Task Force to commence Comment Resolution. The editorial team can be found listed in the Editor's opening report on page 2. The meeting for the rest of day was chaired by Pete Anslow, Chief Editor.

The responses to the comments and actions taken are captured in the comments tool, and therefore will not be noted in the minutes. However, motions made during Comment Resolution will be captured in the meeting minutes.

There were 5 presentations related to comment resolution, these can be found on the meeting web-page at <http://www.ieee802.org/3/bm/public/jul13/index.html> and will be covered in the order of related comments.

Comment Resolution continued until lunch.

Break for lunch at 12:07 p.m.

Reconvened at 1:07 p.m.

Comment Resolution resumes.

Break at 4:10 p.m.

Reconvened at 4:20 p.m.

Comment Resolution resumes.

Recessed for the day at 6:28 p.m.

The Chair announced that meeting will begin at 8:30 a.m. on July 17th.

July 17, 2013

The meeting resumed at 8:30 a.m.

Round of introductions

Pete Anslow, 802.3bm Chief Editor led the Task Force through Comment Resolution.

Break for lunch at 12:15 p.m.
Reconvened at 1:15 p.m.

Comment resolution resumes, and is completed at 4:25 p.m.

The Chair announces that there are 2 house-keeping motions that he intends to bring before the Task Force after which he will schedule presentations related to the SMF 500m objective.

House Keeping Motions

Motion # 1

Move that IEEE P802.3bm Task Force approve the text in IC_802p3bm_oif_0713-v1p0.pdf, with editorial license granted to the Chair (or his appointed agent) as an informal communication to OIF.

Moved: Michael Ressler

Seconded: Tom Palkert

(> 50%)

Y: 13 N: 0 A: 2

Passes

Motion #2

Move to:

– Adopt proposed responses to remaining “non-controversial” comments as indicated in slide 13 of anslow_02_0713_optx.pdf

– Generate Draft 1.1 for TF recirculation from Draft 1.0 and closed comments

Moved: Pete Anslow

Seconded: Peter Stassar

Technical (>= 75% required)

Y: 16 N: 0 A: 1

Passes

Technical Presentations related to 500m SMF objective

Presentation # 5

Title: Parallel SMF (PSM) in the Data Centre - End User Survey -

By: Brad Booth, Independent

See: http://www.ieee802.org/3/bm/public/jul13/flatman_01_0713_optx.pdf

Presentation # 6

Title: 500 m SMF PSM4Draft text update

By: Tom Palkert, Luxtera

See: http://www.ieee802.org/3/bm/public/jul13/palkert_01_0713_optx.pdf

Presentation # 7

Title: 100GBASE-CWDM Baseline Proposal Update

By: Tek Ming Shen, Huawei

See: http://www.ieee802.org/3/bm/public/jul13/zheng_01a_0713_optx.pdf

Presentation # 8

Title: Cost Saving in CWDM Uncooled Solution with FEC for 500m SMF

By: Tek Ming Shen, Huawei

See: http://www.ieee802.org/3/bm/public/jul13/shen_01a_0713_optx.pdf

Presentation # 9

Title: 100GBase-PAM8 Baseline proposal update

By: Arash Farhood, Cortina

See: http://www.ieee802.org/3/bm/public/jul13/farhood_01_0713_optx.pdf

Presentation # 10

Title: 100GBASE-DMT Draft Update

By: Toshiki Tanaka, Fujitsu

See: http://www.ieee802.org/3/bm/public/jul13/tanaka_01_0713_optx.pdf

Presentation # 11

Title: In support of PSM4 for 100GbE

By: Kapil Shrikhande, Dell

See: http://www.ieee802.org/3/bm/public/jul13/shrikhande_01a_0713_optx.pdf

The Chair announced that 500m SMF related presentations would continue on the following day.
Recessed at 6:15 p.m.

July 18, 2013

Meeting adjourned at 9:00 a.m.

Round of introductions

The Chair presented the agenda and general information

http://www.ieee802.org/3/bm/public/jul13/dove_01a_0713_optx.pdf

Technical Presentations

Presentation # 12

Title: SMF Link Costs over Time

By: Brian Welch, Luxtera

See: http://www.ieee802.org/3/bm/public/jul13/welch_01_0713_optx.pdf

Presentation # 13

Title: Low Cost Component Feasibility for 100GBASE-CWDM CFP4

By: Weiqi Li, Photop Technologies

See: http://www.ieee802.org/3/bm/public/jul13/wli_01_0713_optx.pdf

Presentation # 14

Title: Parallel Fiber, a Data Center Operator's Perspective

By: Tom Issenhuth, Microsoft

See: http://www.ieee802.org/3/bm/public/jul13/issenhuth_01_0713_optx.pdf

Presentation # 15

Title: 100G PSM4 Link Model Update, TDP, TxEye Mask & SRS

By: John Petrilla, Avago Technologies

See: http://www.ieee802.org/3/bm/public/jul13/petrilla_01_0713_optx.pdf

Presentation # 16

Title: Specification for 100GBASE-DR4

By: Piers Dawe, Mellanox

See: http://www.ieee802.org/3/bm/public/jul13/dawe_01_0713_optx.pdf

The floor was opened for straw polls and motions

Straw Poll # 1

Straw Poll: I would support adoption of this PMD to satisfy the “at least 500m SMF” objective for inclusion into Draft 1.1 (alphabetical order)

Chicago Rules (Vote for any number of them)

CWDM: 39

DMT: 21

PAM8: 31

PSM4: 53

Motion #3

Move to adopt draft Clause 96 based upon P802d3bm-96_DMT_02.pdf for inclusion into P802.3bm D1.1.

Moved: Toshiki Tanaka

Seconded: Hideki Isono

Technical ($\geq 75\%$ required)

Y: 27 N: 51 A: 31

Fails

Motion #4

Move to adopt draft Clause 96 based upon P802d3bm-96_PAM8_02.pdf for inclusion into P802.3bm D1.1.

Moved: Arash Farhood

Seconded: Will Bliss

Technical ($\geq 75\%$ required)

Y: 32 N: 48 A: 34

Fails

Motion # 5

Move to adopt draft Clause 96 based upon P802d3bm-96_CWDM_02.pdf for inclusion into P802.3bm D1.1.

Moved: Tek-Ming Shen

Seconded: Zeng Li

Technical ($\geq 75\%$ required)

Y: 37 N: 55 A: 27

Fails

Motion # 6

Move to adopt draft Clause 96 based upon P802d3bm-96_PSM4_02.pdf for inclusion into P802.3bm D1.1.

Moved: Tom Palkert

Seconded: John Petrilla

Technical ($\geq 75\%$ required)

Y: 48 N: 45 A: 26

Fails

The final presentation on the agenda, the Editor's closing report was subsequently covered.

Presentation # 17

Title: Editor's closing report

By: Pete Anslow, Ciena (802.3bm Chief Editor)

See: http://www.ieee802.org/3/bm/public/jul13/anslow_03_0713_optx.pdf

Meeting was adjourned at 12:01 p.m.

IEEE 802.3bm July 2013 plenary meeting attendance from sign-up sheet

| Last Name | First Name | Affiliation | Employer | 16-Jul | 17-Jul | 18-Jul |
|-----------|------------|----------------------------|-----------------------|--------|--------|--------|
| Abbas | Ghani | Ericsson | | | Y | Y |
| Anslow | Pete | Ciena | | Y | Y | Y |
| Baldwin | Thananya | Ixia | | | Y | Y |
| Ben-Artzi | Liav | Marvell | | | | Y |
| Bergey | Chris | Luxtera | | | Y | Y |
| Bhatt | Vipul | Cisco | | | | Y |
| Bliss | Will | Broadcom | | | | Y |
| Booth | Brad | Independent | | | Y | Y |
| Bouda | Martin | Fujitsu | Fujitsu | Y | Y | Y |
| Brown | Matt | Applied Micro | | | | Y |
| Chalupsky | David | Intel | Intel | | Y | |
| Chang | Xin | Huawei | | | | Y |
| Choudhury | Mabud | Commscope | | | Y | Y |
| Cibula | Pets | Intel | Intel | | Y | Y |
| Cole | Chris | Finisar | | | | Y |
| Darshan | Yair | Microsemi | Microsemi | | Y | |
| Dawe | Piers | Mellanox | Mellanox | Y | Y | Y |
| Diab | Wael | Broadcom | Broadcom | Y | Y | |
| Flatman | Alan | LAN Technologies | | | Y | |
| Forbes | Harry | Nexans Inc | | | | Y |
| Garcia | Modesto | Texas Instruments | Texas Instruments | Y | Y | Y |
| Ghiasi | Ali | Broadcom | | Y | | |
| Gong | Zhigang | JDSU | | | Y | Y |
| Gustlin | Mark | XILINX | | | | Y |
| Hammond | Bernie | TE | | | | Y |
| Hangchun | Xu | Accelink Technologies | Accelink Technologies | Y | Y | Y |
| Herman | Carl | CommScope | CommScope | | Y | Y |
| Hiramoto | Kiyo | Oclaro | | | | Y |
| Holden | Brian | Kandou | Kandou | | | Y |
| Isono | Hideki | Fujitsu Optical Components | Fujitsu | Y | Y | Y |
| Issenhuth | Tom | Microsoft | | | | Y |
| Jewell | Jack | Independent | | | | Y |
| Kawatsu | Yasuaki | Hitachi Metals | | Y | Y | Y |
| Kelsen | Michael | TWC | TWC | | | Y |
| Keshavan | Kumar | Cadence Design | | | | Y |
| Kimmtli | Myles | Emuley | | | | Y |
| King | Jonathan | Finisar | | Y | Y | Y |

| | | | | | | |
|---------------|-----------|------------------------|-----------------|---|---|---|
| Kipp | Scott | Brocade | | | | Y |
| Kochuparambil | Beth | Cisco | | | | Y |
| Kolesar | Paul | Commscope | | | Y | Y |
| Latchman | Ryan | Mindspeed | | | Y | |
| LeCheminant | Greg | Agilent Technologies | | Y | Y | |
| Lewis | Dave | JDSU | | Y | Y | Y |
| Li | Mike | Altera | | Y | Y | |
| Li | Shaohua | Brocade | | | | Y |
| Li | Weiqi | Photop | | Y | Y | Y |
| Lingle | Robert | OFS | | | Y | |
| Lusted | Kent | Intel | Intel | | | Y |
| Maki | Jeffery | Juniper | | | Y | Y |
| Martin | Arlon | Kotura | | | | Y |
| Masuda | Takeo | Petra | | | | Y |
| Maynes | Curt | 3M | 3M | Y | Y | Y |
| McDermott | Tom | Fujitsu Labs | | | Y | Y |
| McDonough | John | NEC America | | | Y | |
| Mei | Richard | Commscope | | | | Y |
| Melitz | Rich | Intel | | | | Y |
| Mooney | Paul | Spirent | | | | Y |
| Moore | Charles | Avago | | | | Y |
| Nakamoto | Ed | Spirent | | Y | | Y |
| Nordin | Ron | Panduit | | | | Y |
| Ofelt | David | Juniper | | | Y | Y |
| Ogura | Ichiro | PETRA | | | | Y |
| Palkert | Tom | Xilinx, Molex, Luxtera | | | Y | Y |
| Parthasarathy | Vasudevan | Broadcom | | | Y | Y |
| Pepper | Jerry | Ixia | | | Y | Y |
| Petrilla | John | Avago Technologies | | Y | Y | Y |
| Prendergast | James | IEEE | IEEE | | | Y |
| Rabinovich | Rick | Alcatel Lucent | | Y | Y | Y |
| Ran | Adee | Intel | | | | Y |
| Rannow | Randy | APIC Corp | APIC Corp | | Y | |
| Rao | Ram | Oclaro | Oclaro | | | Y |
| Ressl | Michael | Hitachi Cable America | Hitachi | Y | Y | Y |
| Ria | Himi | Hitachi | | | | Y |
| Rotolo | Salvatore | ST Microelectronics | ST Micro | Y | Y | Y |
| Salunke | Vineet | Cisco | | | | Y |
| Saner | Martin | SNT | SNT | | Y | |
| Sasaki | Yasuo | TE Connectivity | TE Connectivity | Y | Y | Y |
| Shen | Tek-Ming | Huawei Technologies | Huawei | Y | Y | Y |
| Song | Xiaolu | Huawei | | Y | Y | |

| | | | | | | |
|------------|----------|------------------------------|--------------|---|---|---|
| Sprague | Ted | Infinera | | Y | | Y |
| Stassar | Peter | Huawei | Huawei | Y | Y | Y |
| Stevens | Daniel | Fujitsu Semiconductor Europe | | | | Y |
| Suping | Zhai | Huawei | | Y | Y | Y |
| Swanson | Steve | Corning Inc | Corning Inc | Y | Y | |
| Szczepanek | Andre | Inphi | Inphi | Y | | Y |
| Takahata | Kiyoto | NTT | | Y | Y | Y |
| Tanaka | Toshiki | Fujitsu Labs | Fujitsu Labs | Y | Y | Y |
| Timmins | Ian | OCC | | Y | | |
| Tipper | Alan | Semtech | | | Y | Y |
| Tomoo | Takahara | Fujitsu Lab | | | Y | Y |
| Tracy | Nathan | TE Connectivity | | Y | Y | Y |
| Tremblay | Francois | Semtech | | Y | Y | Y |
| Trowbridge | Steve | Alcatel Lucent | | Y | Y | Y |
| Tsutsumi | Satoshi | Hitachi | | | | Y |
| Ulrichs | Ed | Sourcephotonics | | Y | Y | Y |
| Vaden | Sterling | Optical Cable | | | | Y |
| Vanderlaan | Paul | Nexans Inc | | | Y | Y |
| Vijn | Arien | AMS-IX | | | | Y |
| Wagner | Bob | Panduit | | | | Y |
| Wang | Robert | Intel | | | | Y |
| Welch | Brian | Luxtera | | Y | Y | Y |
| Wirtz | Mike | Semtech | | | Y | Y |
| Wong | CK | FCI | FCI | Y | Y | Y |
| Wong | Henry | Huawei | | | | Y |
| XinYuan | Wang | Huawei | | | | Y |
| Xu | Yu | Huawei | | | | Y |
| Zbinden | Eric | Samtec | Samtec | Y | Y | Y |
| Zeng | Li | Huawei | | Y | Y | Y |
| Zhao | Wenyu | CATR China | | Y | Y | Y |
| Zivny | Pavel | Tektronix | | | | Y |

Number of attendees who signed the sheet on at least one day = 111